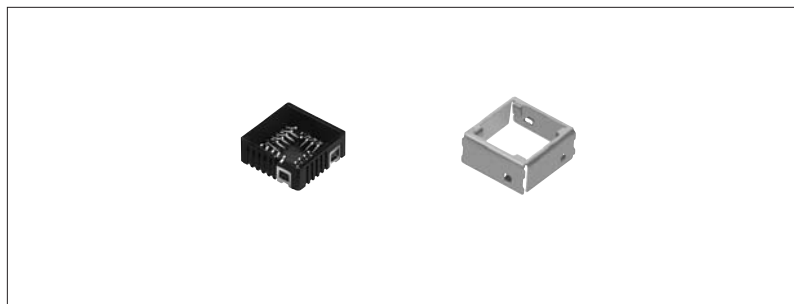


Connector for CMOS Camera Module

SCKA Series



Compact size achieved from thin body-forming molding.



Features

- Camera module detaching function.
- Locking mechanism to prevent the camera module from falling.
- Shield cover included.
- Vibration resistant contact structure.
- Provided with an adsorption area allowing automatic mounting.

Applications

- For camera-equipped mobile phones

Typical Specifications

Items		Specifications
Dimensions	6×6mm module type	7×7×3.1mm
Structure	Mounting system	Surface mounting type
Performance	Operating temperature range	−25℃ to +85℃
	Voltage proof	100V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycles	10cycles

Product Line

Items	Product	Minimum packing unit (pcs.)	Packing system	Product No.	Drawing No.
6×6mm module type	Connector	2,000	Taping	SCKA2A0100	1
	Cover	5,000	—	JSCKA0002A	2

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

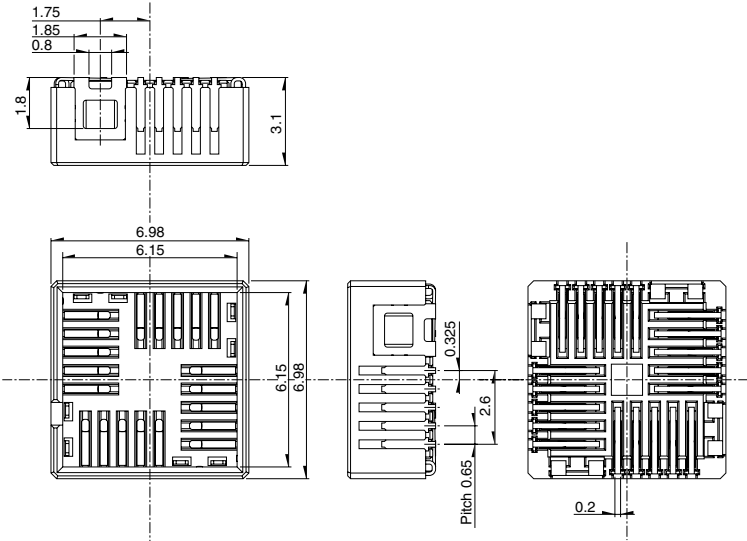
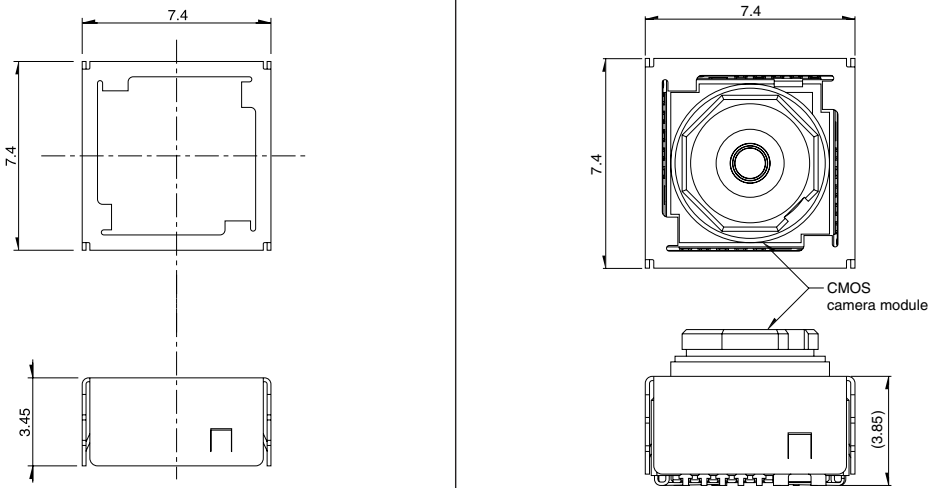
For Express Card™

For CMOS Camera Module

Dimensions
6×6mm module type

Unit:mm

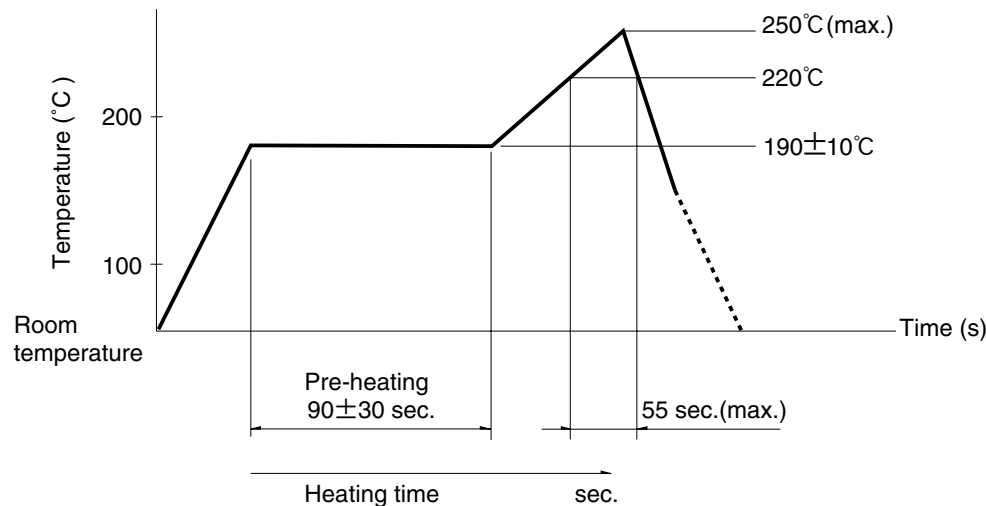
- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For W-SIM
- For Memory Stick Micro™
- For Memory Stick™
- Combine Type
- For Compact Flash™
- For PC cards supporting CardBus
- For Express Card™
- For CMOS Camera Module

No.	Style	
1	Connector	
	PC board mounting hole dimensions (Viewed from the mounting face side)	
2	Style	Connector/Cover combination diagram (Reference)
	Cover	

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.

For
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